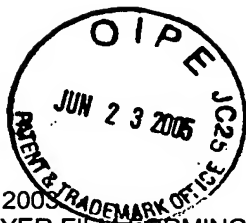


In re Application of: MIKAMI et al.
 Application No. 10/732,798
 Filed: December 11, 2003
 For:



AN UNDERLAYER FILM FORMING MATERIAL FOR COPPER, METHOD FOR A FORMING UNDERLAYER FILM FOR COPPER, AN UNDERLAYER FILM FOR COPPER, AND A SEMICONDUCTOR DEVICE

U.S. Patent and Trademark Office
 Customer Service Window, Mail Stop Amendment
 Randolph Building
 401 Dulany Street
 Alexandria, VA 22314

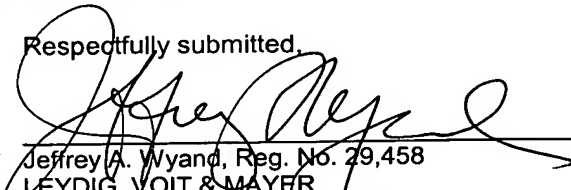
Sir:

- ☐ Small entity status is claimed for this application under 37 CFR 1.27.
- ☐ Petition for an extension of time for the period noted below, as well as for any additional period necessary to render the present submission timely. Please charge Deposit Account No. 12-1216 for the appropriate petition fee.
- ☐ Other:
- ☐ Please charge Deposit Account No. 12-1216 in the total amount indicated below. A duplicate copy of this transmittal sheet is enclosed herewith.

					SMALL ENTITY		OTHER THAN A SMALL ENTITY	
TIME EXTENSION PETITION FEE		none			\$ 0.00		\$ 0.00	
	subtract time extension fee previously paid	none			(\$ 0.00)		(\$ 0.00)	
CLAIM FEE	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NUMBER PREVIOUSLY PAID FOR	EXTRA CLAIMS PRESENT	RATE	ADD'L CLAIM FEE	RATE	ADD'L CLAIM FEE
TOTAL		MINUS		=	x 25=	\$	x 50=	\$
INDEPENDENT		MINUS		=	x 100=	\$	x 200=	\$
<input type="checkbox"/>	FIRST PRESENTATION OF MULTIPLE CLAIM				+ 180=	\$	+ 360=	\$
TOTAL AMOUNT TO BE CHARGED TO DEPOSIT ACCOUNT					TOTAL	\$	TOTAL	\$

- ☒ The Commissioner is hereby authorized to charge any deficiencies in the following fees associated with this communication or credit any overpayment to Deposit Account No. 12-1216.
- ☒ Any filing fees under 37 CFR 1.16 for the presentation of extra claims.
- ☒ Any patent application processing fees under 37 CFR 1.17.

Respectfully submitted,


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Date:  23, 2005
 JAW/tps
 Amendment or ROA Transmittal (Revised 1/14/05)



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Patent Application No. 10/732,798

Applicant: MIKAMI et al.

Filed: December 11, 2003

TC/AU: 2891

Examiner: C. Wilson

Docket No.: 402906

Customer No.: 23548

Commissioner for Patents
U.S. Patent and Trademark Office
Customer Service Window, Mail Stop Amendment
Randolph Building
401 Dulany Street
Alexandria, VA 22314

REPLY TO OFFICE ACTION

Sir:

In reply to the Office Action dated May 25, 2005, please enter the following amendments and consider the following remarks.

Amendments to the Title begin on page 2 of this paper.

Remarks/Arguments begin on page 3 of this paper.

AMENDMENTS TO THE TITLE

Please replace title with:

~~AN UNDERLAYER FILM FORMING MATERIAL FOR COPPER, METHOD FOR
A FORMING UNDERLAYER FILM FOR COPPER, AN UNDERLAYER FILM FOR
COPPER, AND A SEMICONDUCTOR DEVICE INCLUDING THE UNDERLAYER~~
FILM